

L Number	Hits	Search Text	DB	Time stamp
1	0	(light-emitting-diode light-emitter) and wafer-bond\$3 and solder	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 10:27
2	0	(light-emitting-diode light-emitter) and wafer-bond\$3 with (intermetallic metal metallic)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 10:29
3	3	(light-emitting-diode light-emitter diode) and wafer-bond\$3 with (intermetallic metal metallic)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 11:18
4	1	("5508718").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 10:38
5	1	("5008718").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 10:43
6	15	chen-shi-ming.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 10:43
7	25	(light-emitting-diode light-emitter diode) and (metal\$3 near3 eutectic near3 bond\$3) and transparen\$	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/25 11:20